

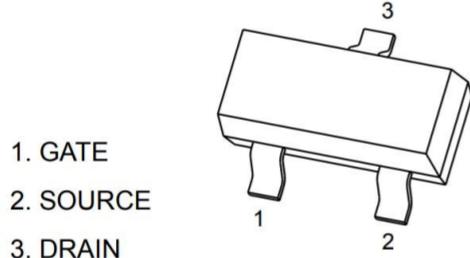
## Product Summary

- $V_{DS}$  25 V
- $I_D$  0.9A
- $R_{DS(ON)}$  ( $V_{GS}=4.5V, I_D=0.3A$ )  $\leq 1.05\Omega$
- ESD protected gate, typical 6kV (HBM)

## Application

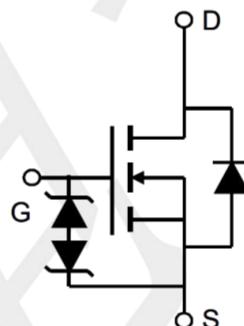
- Interfacing Switching
- Load Switch
- Portable equipment and battery
- DC/DC Converter

## Package and Pin Configuration



SOT23

## Circuit diagram



## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	25	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	0.9	A
Pulsed Drain Current ( $t = 100 \mu s$ )	$I_{DM}$	2.5	A
Electrostatic Discharge Rating Human Body Model	ESD	6.0	kV
Maximum Power Dissipation	$P_D$	0.85	W
Operating Junction Temperature Range	$T_J$	+155	°C
Storage Temperature Range	$T_{stg}$	-55 to +150	°C

## Thermal Characteristic

PARAMETER	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient( $t \leq 10s$ )	$R_{\theta JA}$	357	°C/W

Note : When mounted on 1" square PCB (FR4 material).

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D= 10\mu\text{A}$	$BV_{DSS}$	25	--	--	V
Gate-Source Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D= 250\mu\text{A}$	$V_{GS(\text{th})}$	0.6	1.0	1.5	V
Gate-Source Leakage	$V_{DS}=0\text{V}$ , $V_{GS}= \pm 12\text{V}$	$I_{GSS}$	--	--	$\pm 0.5$	$\mu\text{A}$
Zero Gate Voltage Drain Current	$V_{DS}= 25\text{V}$ , $V_{GS}=0\text{V}$	$I_{DSS}$	--	--	1.0	$\mu\text{A}$
Drain-Source On-State Resistance (Note 1)	$V_{GS}= 4.5\text{V}$ , $I_D= 0.3\text{A}$ $V_{GS}= 3.0\text{V}$ , $I_D= 0.2\text{A}$	$R_{DS(\text{on})}$	--	0.40	1.05	$\Omega$
Forward Transconductance (Note 2)	$V_{DS}= 15\text{V}$ , $I_D= 0.2\text{A}$		--	0.57	2.10	
<b>Dynamic</b> (Note 2)						
Input Capacitance	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $F = 1.0\text{MHz}$	$C_{iss}$	--	50	--	$\text{pF}$
Output Capacitance		$C_{oss}$	--	16	--	
Reverse Transfer Capacitance		$C_{rss}$	--	11	--	
<b>Switching</b>						
Turn-On Delay Time (Note 3)	$V_{DS} = 25\text{V}$ , $I_D = 0.2\text{A}$ , $V_{GEN} = 10\text{V}$ , $R_G = 10\Omega$	$t_{d(on)}$	--	35	--	$\text{nS}$
Rise Time (Note 3)		$t_r$	--	61	--	
Turn-Off Delay Time (Note 3)		$t_{d(off)}$	--	55	--	
Fall Time (Note 3)		$t_f$	--	35	--	
Total Gate Charge	$V_{DS} = 25\text{V}$ , $I_D = 0.3\text{A}$ , $V_{GS} = 10\text{V}$	$Q_g$	--	2.5	--	$\text{nC}$
Gate-Source Charge		$Q_{gs}$	--	1.1	--	
Gate-Drain Charge		$Q_{gd}$	--	0.35	--	
<b>Source-Drain Diode Ratings and Characteristics</b> (Note 2)						
Forward Voltage	$V_{GS} = 0\text{V}$ , $I_F = 0.1\text{A}$	$V_{SD}$	--	0.85	1.2	V
Continuous Source Current	Integral reverse diode in the MOSFET	$I_s$	--	--	0.9	A
Pulsed Current (Note 1)		$I_{SM}$	--	--	2.5	A

Notes:

1. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

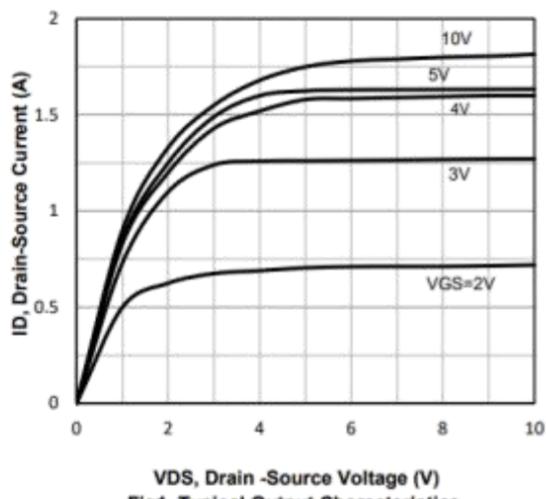


Fig1. Typical Output Characteristics

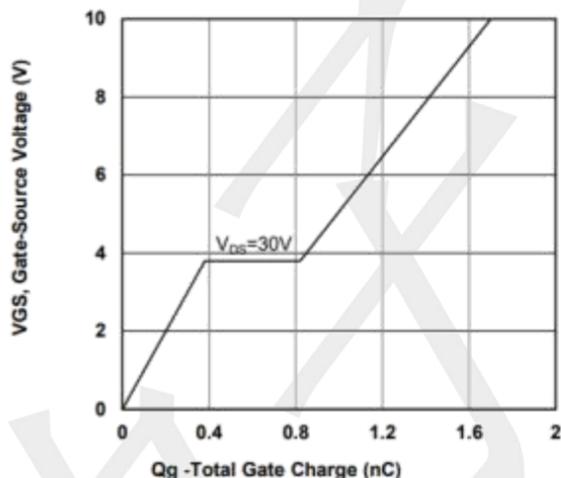


Fig2. Typical Gate Charge Vs. Gate-Source Voltage

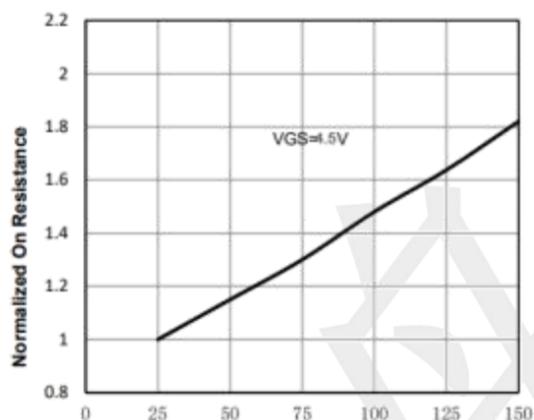


Fig3. Normalized On-Resistance Vs. Temperature

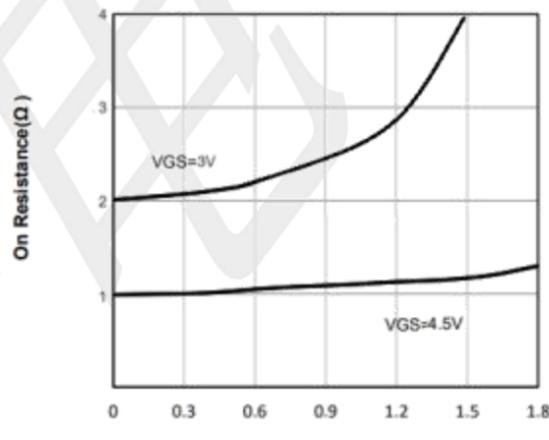


Fig4. On-Resistance Vs. Drain-Source Current

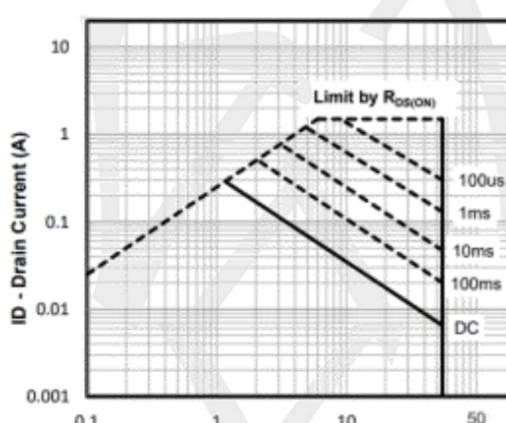


Fig5. Maximum Safe Operating Area

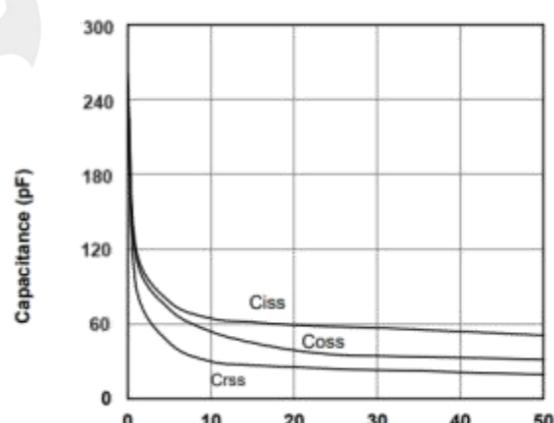
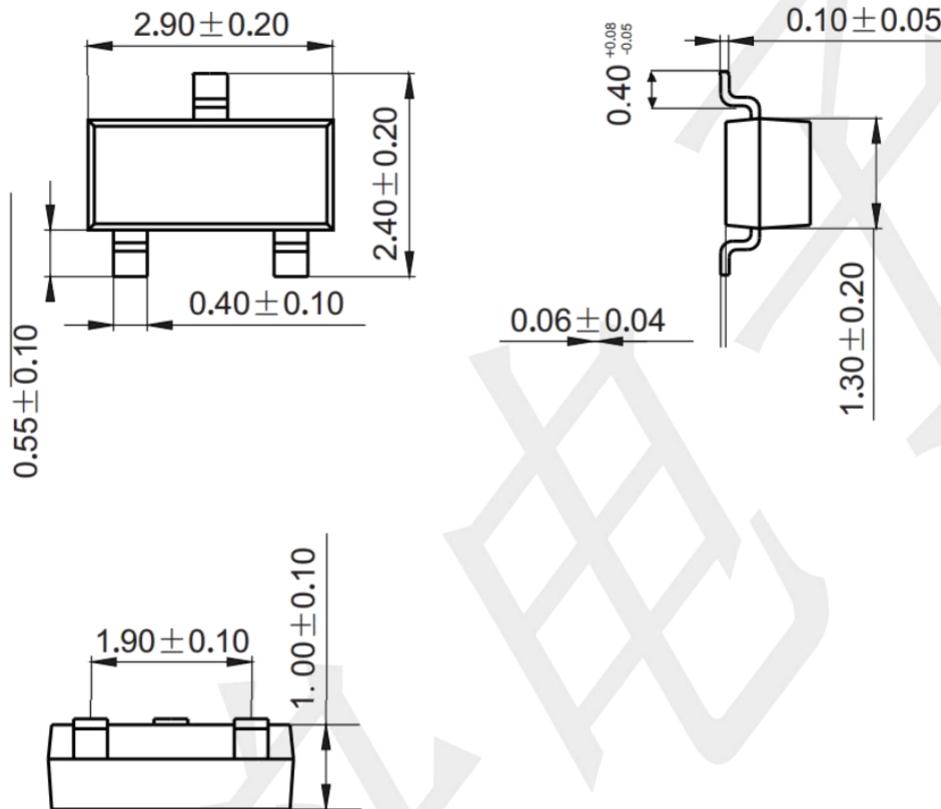


Fig6. Typical Capacitance Vs. Drain-Source Voltage

### Package Outline Dimensions (unit: mm)

SOT-23



### Mounting Pad Layout (unit: mm)

